TRADEMARK ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	SECURITY INTEREST

CONVEYING PARTY DATA

Name	Formerly	Execution Date	Entity Type
FLIPCHIP INTERNATIONAL, LLC		10/24/2011	LIMITED LIABILITY COMPANY: DELAWARE

RECEIVING PARTY DATA

Name:	WELLS FARGO BANK, NATIONAL ASSOCIATION
Street Address:	100 West Washington Street, 15th Floor
Internal Address:	Wells Fargo Plaza, MAC S4101-158
City:	Phoenix
State/Country:	ARIZONA
Postal Code:	85003
Entity Type:	banking institution: ARIZONA

PROPERTY NUMBERS Total: 5

Property Type	Number	Word Mark
Registration Number:	3332305	ELITECSP
Registration Number:	3332289	ELITEFC
Registration Number:	2980315	FLIPCHIP INTERNATIONAL
Registration Number:	2929612	SPHERON
Registration Number:	2496509	ULTRA CSP

CORRESPONDENCE DATA

Fax Number: (602)364-7070
Phone: 602-364-7000
Email: allan.watts@bryancave.com
Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.
Correspondent Name: Bryan Cave LLP
Address Line 1: Two North Central Avenue, Suite 2200
Address Line 2: Allan W. Watts

CH $140.00 3332305

Address Line 4:	Phoenix, ARIZONA 85004
ATTORNEY DOCKET NUMBER:	0223157
NAME OF SUBMITTER:	Allan W. Watts
Signature:	/Allan W. Watts/
Date:	11/10/2011

Total Attachments: 29
source=Second Amended and Restated Patent and Trademark Security Agreement#page1.tif
source=Second Amended and Restated Patent and Trademark Security Agreement#page2.tif
source=Second Amended and Restated Patent and Trademark Security Agreement#page3.tif
source=Second Amended and Restated Patent and Trademark Security Agreement#page4.tif
source=Second Amended and Restated Patent and Trademark Security Agreement#page5.tif
source=Second Amended and Restated Patent and Trademark Security Agreement#page6.tif
source=Second Amended and Restated Patent and Trademark Security Agreement#page7.tif
source=Second Amended and Restated Patent and Trademark Security Agreement#page8.tif
source=Second Amended and Restated Patent and Trademark Security Agreement#page9.tif
source=Second Amended and Restated Patent and Trademark Security Agreement#page10.tif
source=Second Amended and Restated Patent and Trademark Security Agreement#page11.tif
source=Second Amended and Restated Patent and Trademark Security Agreement#page12.tif
source=Second Amended and Restated Patent and Trademark Security Agreement#page13.tif
source=Second Amended and Restated Patent and Trademark Security Agreement#page14.tif
source=Second Amended and Restated Patent and Trademark Security Agreement#page15.tif
source=Second Amended and Restated Patent and Trademark Security Agreement#page16.tif
source=Second Amended and Restated Patent and Trademark Security Agreement#page17.tif
source=Second Amended and Restated Patent and Trademark Security Agreement#page18.tif
source=Second Amended and Restated Patent and Trademark Security Agreement#page19.tif
source=Second Amended and Restated Patent and Trademark Security Agreement#page20.tif
source=Second Amended and Restated Patent and Trademark Security Agreement#page21.tif
source=Second Amended and Restated Patent and Trademark Security Agreement#page22.tif
source=Second Amended and Restated Patent and Trademark Security Agreement#page23.tif
source=Second Amended and Restated Patent and Trademark Security Agreement#page24.tif
source=Second Amended and Restated Patent and Trademark Security Agreement#page25.tif
source=Second Amended and Restated Patent and Trademark Security Agreement#page26.tif
source=Second Amended and Restated Patent and Trademark Security Agreement#page27.tif
source=Second Amended and Restated Patent and Trademark Security Agreement#page28.tif
source=Second Amended and Restated Patent and Trademark Security Agreement#page29.tif

SECOND AMENDED AND RESTATED PATENT AND TRADEMARK SECURITY AGREEMENT

This Second Amended and Restated Patent and Trademark Security Agreement (this "Agreement"), dated as of October 24, 2011, is made by and between FLIPCHIP INTERNATIONAL, LLC, a Delaware limited liability company having a business location at the address set forth below next to its signature (the "Debtor"), and WELLS FARGO BANK, NATIONAL ASSOCIATION, acting through its Wells Fargo Business Credit operating division having a business location at the address set forth below next to its signature (the "Secured Party").

Recitals

The Debtor and the Secured Party are parties to a Third Amended and Restated Credit and Security Agreement of even date herewith (as the same may hereafter be amended, supplemented or restated from time to time, the "Credit Agreement") setting forth the terms on which the Secured Party may now or hereafter extend credit to or for the account of the Debtor.

As a condition to extending credit to or for the account of the Debtor, the Secured Party has required the execution and delivery of this Agreement by the Debtor.

ACCORDINGLY, in consideration of the mutual covenants contained in the Loan Documents (as defined in the Credit Agreement) and herein, the parties hereby agree as follows:

1. Definitions. All terms defined in the Recitals hereto or in the Credit Agreement that are not otherwise defined herein shall have the meanings given to them therein. In addition, the following terms have the meanings set forth below:

"Event of Default" shall have the meaning given in Section 5.

"Obligations" means each and every debt, liability and obligation of every type and description arising under or in connection with any Loan Document (as defined in the Credit Agreement) which the Debtor may now or at any time hereafter owe to the Secured Party, whether such debt, liability or obligation now exists or is hereafter created or incurred and whether it is or may be direct or indirect, due or to become due, absolute or contingent, primary or secondary, liquidated or unliquidated, independent, joint, several or joint and several, and including specifically, but not limited to, the Obligations (as defined in the Credit Agreement).

"Patents" means all of the Debtor's right, title, interest and license rights in and to patents, applications for patents, and licensed Delphi Patents pursuant to the Technology Transfer Agreement (including, without limitation, any and all continuations, continuations-in-part, re-issues, divisions, extensions, substitutes, renewals, reexaminations and foreign counterparts thereof) and fees or royalties with respect to each, and including without limitation the right to sue for past infringement and

TRADEMARK
REEL: 004659 FRAME: 0250

damages therefor, and licenses thereunder, all as presently existing or hereafter arising or acquired, including without limitation the patents listed on **Exhibit A**.

"Security Interest" has the meaning given to it in Section 2(a).

"Trademarks" means all of the Debtor's right, title and interest in and to: (i) trademarks, service marks, collective membership marks, registrations and applications for registration for each, and the respective goodwill associated with each; (ii) licenses, fees or royalties with respect to each, whether or not such trademarks, service marks, collective membership marks are registered with any state, federal, or national government; (iii) the right to sue for past, present and future infringement, dilution and damages therefor; and (iv) licenses thereunder, all as presently existing or hereafter arising or acquired, including, without limitation, the marks listed on **Exhibit B**.

2. Security Interest.

(a) The Debtor hereby irrevocably pledges and assigns to and grants the Secured Party a security interest (the "Security Interest"), with power of sale to the extent permitted by law, in the Patents and in the Trademarks to secure payment of the Obligations. As set forth in the Credit Agreement, the Security Interest is coupled with a security interest in substantially all of the personal property of the Debtor.

(b) The foregoing notwithstanding, and with respect to the grant of Security Interests hereunder only, the terms Patents and Trademarks shall not include the following "Excluded Collateral": Debtor's Patents and Trademarks, in each case subject to any agreement (A) the terms of which expressly prohibit the granting of a lien or an assignment with respect to such item and then only to the extent (i) any necessary consent shall not have been obtained and (ii) the terms of any such agreement are not in contravention of Section 9-408 of the Uniform Commercial Code, or (B) with respect to which the granting of liens and security interests therein would otherwise result in a loss of rights therein by operation of law. Debtor hereby represents and warrants to the Secured Party that the Excluded Collateral, when taken as a whole, is not material to the operations, business, properties or condition of Debtor.

3. Representations, Warranties and Agreements. The Debtor represents, warrants and agrees as follows:

(a) ***Existence; Authority***. The Debtor is a limited liability company duly organized, validly existing and in good standing under the laws of its state of organization, and this Agreement has been duly and validly authorized by all necessary organizational action on the part of the Debtor.

(b) ***Patents***. Exhibit A accurately lists all Patents owned or controlled by the Debtor as of the date hereof, or to which the Debtor has a right as of the date

TRADEMARK
REEL: 004659 FRAME: 0251

hereof to have assigned to it, and accurately reflects the existence and status of applications and letters patent pertaining to the Patents as of the date hereof. If after the date hereof, the Debtor owns, controls or has a right to have assigned to it any Patents not listed on Exhibit A, or if Exhibit A ceases to accurately reflect the existence and status of applications and letters patent pertaining to the Patents, then the Debtor shall within 60 days provide written notice to the Secured Party with a replacement Exhibit A, which upon acceptance by the Secured Party shall become part of this Agreement.

(c) ***Trademarks***. Exhibit B accurately lists all Trademarks owned or controlled by the Debtor as of the date hereof and accurately reflects the existence and status of Trademarks and all applications and registrations pertaining thereto as of the date hereof; provided, however, that Exhibit B need not list common law marks (i.e., Trademarks for which there are no applications or registrations) which are not material to the Debtor's or any Affiliate's business(es). If after the date hereof, the Debtor owns or controls any Trademarks not listed on Exhibit B (other than common law marks which are not material to the Debtor's or any Affiliate's business(es)), or if Exhibit B ceases to accurately reflect the existence and status of applications and registrations pertaining to the Trademarks, then the Debtor shall promptly provide written notice to the Secured Party with a replacement Exhibit B, which upon acceptance by the Secured Party shall become part of this Agreement.

(d) **INTENTIONALLY LEFT BLANK.**

(e) ***Title***. The Debtor has absolute title to each Patent and each Trademark listed on Exhibits A and B, free and clear of all Liens except Permitted Liens. The Debtor (i) will have, at the time the Debtor acquires any rights in Patents or Trademarks hereafter arising, absolute title to each such Patent or Trademark free and clear of all Liens except Permitted Liens, and (ii) will keep all Patents and Trademarks free and clear of all Liens except Permitted Liens.

(f) ***No Sale***. Except as permitted by the terms of Section 6.18 of the Credit Agreement and Section 4 of this Agreement, the Debtor will not assign, transfer, encumber or otherwise dispose of the Patents or Trademarks, or any interest therein, without the Secured Party's prior written consent.

(g) ***Defense***. Except as permitted by the terms of Section 6.14(b) of the Credit Agreement, the Debtor will at its own expense and using commercially reasonable efforts to protect and defend the Patents and Trademarks against all claims or demands of all Persons other than those holding Permitted Liens.

(h) ***Maintenance***. Unless, in the reasonable determination of the Debtor, (i) the maintenance costs of such Patents and Trademarks outweigh the usefulness of such Patents and Trademarks to the business of the Debtor and (ii) the loss of such Patents and Trademarks would not be disadvantageous in any material respect to the Lender, the Debtor will at its own expense maintain the Patents and the Trademarks, including, but not limited to, filing all applications to obtain letters patent or trademark registrations and all affidavits, maintenance fees, filing fees, annuities, and renewals

TRADEMARK
REEL: 004659 FRAME: 0252

possible with respect to letters patent, trademark registrations and applications therefor. The Debtor covenants that unless, in the reasonable determination of the Debtor, (i) the maintenance costs of such Patent or Trademark outweigh the usefulness of such Patent or Trademark to the business of the Debtor and (ii) the loss of such Patent or Trademark would not be disadvantageous in any material respect to the Lender, it will not abandon nor fail to pay any maintenance fee, filing fee or annuity due and payable on any Patent or Trademark, or fail to file any required affidavit or renewal in support thereof, without first providing the Secured Party: (i) sufficient written notice, of at least 30 days, to allow the Secured Party to timely pay any such maintenance fees or annuities which may become due on any Patents or Trademarks, or to file any affidavit or renewal with respect thereto, and (ii) a separate written power of attorney or other authorization to pay such maintenance fees, filing fees or annuities, or to file such affidavit or renewal, should such be necessary or desirable.

(i) ***Secured Party's Right to Take Action***. If the Debtor fails to perform or observe any of its covenants or agreements set forth in this Section 3, and if such failure continues for a period of ten (10) calendar days after the Secured Party gives the Debtor written notice thereof (or, in the case of the agreements contained in subsection (h), immediately upon the occurrence of such failure, without notice or lapse of time), or if the Debtor notifies the Secured Party that it intends to abandon a Patent or Trademark which it is obligated to maintain pursuant to the terms of the Credit Agreement, the Secured Party may (but need not) perform or observe such covenant or agreement or take steps to prevent such intended abandonment on behalf and in the name, place and stead of the Debtor (or, at the Secured Party's option, in the Secured Party's own name) and may (but need not) take any and all other actions which the Secured Party may reasonably deem necessary to cure or correct such failure or prevent such intended abandonment.

(j) ***Costs and Expenses***. Except to the extent that the effect of such payment would be to render any loan or forbearance of money usurious or otherwise illegal under any applicable law, the Debtor shall pay the Secured Party on demand the amount of all moneys expended and all costs and expenses (including reasonable attorneys' fees and disbursements) incurred by the Secured Party in connection with or as a result of the Secured Party's taking action under subsection (i) or exercising its rights under Section 6, together with interest thereon from the date expended or incurred by the Secured Party at the Default Rate.

(k) ***Power of Attorney***. To facilitate the Secured Party's taking action under subsection (i) and exercising its rights under Section 6, the Debtor hereby irrevocably appoints (which appointment is coupled with an interest) the Secured Party, or its delegate, as the attorney-in-fact of the Debtor with the right (but not the duty) from time to time to create, prepare, complete, execute, deliver, endorse or file, in the name and on behalf of the Debtor, any and all instruments, documents, applications, financing statements, and other agreements and writings required to be obtained, executed, delivered or endorsed by the Debtor under this Section 3 (including replacement Exhibits), or, necessary for the Secured Party, after an Event of Default, to enforce or use the Patents or Trademarks or to grant or issue any exclusive or non-exclusive license

TRADEMARK
REEL: 004659 FRAME: 0253

under the Patents or Trademarks to any third party, or to sell, assign, transfer, pledge, encumber or otherwise transfer title in or dispose of the Patents or Trademarks to any third party. The Debtor hereby ratifies all that such attorney shall lawfully do or cause to be done by virtue hereof. The power of attorney granted herein shall terminate upon the termination of the Credit Agreement as provided therein and the payment and performance of all Obligations.

(l) ***Further Assurances***. The Debtor, upon the written request of the Secured Party, shall execute and deliver such further documents as may be reasonably necessary to carry out the intent of this Agreement and to perfect and preserve the rights and interests of the Secured Party hereunder and the priority thereof.

4. Debtor's Use of the Patents and Trademarks. The Debtor shall be permitted to control and manage the Patents and Trademarks, including the right to exclude others from making, using or selling items covered by the Patents and Trademarks and any licenses thereunder, in the same manner and with the same effect as if this Agreement had not been entered into, so long as no Event of Default occurs and remains uncured.

5. Events of Default. Each of the following occurrences shall constitute an event of default under this Agreement (herein called "Event of Default"): (a) an Event of Default, as defined in the Credit Agreement, shall occur; or (b) the Debtor shall fail promptly to observe or perform any covenant or agreement herein binding on it; or (c) any of the representations or warranties contained in Section 3 shall prove to have been incorrect in any material respect when made.

6. Remedies. Upon the occurrence of an Event of Default and at any time thereafter, the Secured Party may, at its option, take any or all of the following actions:

(a) The Secured Party may exercise any or all remedies available under the Credit Agreement.

(b) The Secured Party may sell, assign, transfer, pledge, encumber or otherwise dispose of the Patents and Trademarks.

(c) The Secured Party may enforce the Patents and Trademarks and any licenses thereunder, and if Secured Party shall commence any suit for such enforcement, the Debtor shall, at the request of Secured Party, do any and all lawful acts and execute any and all proper documents required by Secured Party in aid of such enforcement.

7. Miscellaneous. This Agreement can be waived, modified, amended, terminated or discharged, and the Security Interest can be released, only explicitly in a writing signed by the Secured Party. A waiver signed by the Secured Party shall be effective only in the specific instance and for the specific purpose given. Mere delay or failure to act shall not preclude the exercise or enforcement of any of the Secured Party's rights or remedies. All rights and remedies of the Secured Party shall be cumulative and may be exercised singularly or concurrently, at the Secured Party's option, and the exercise or enforcement of anyone such right or remedy shall neither be a condition to nor bar the exercise or enforcement of any other. All

TRADEMARK
REEL: 004659 FRAME: 0254

notices to be given to Debtor under this Agreement shall be given in the manner and with the effect provided in the Credit Agreement. The Secured Party shall not be obligated to preserve any rights the Debtor may have against prior parties, to realize on the Patents and Trademarks at all or in any particular manner or order, or to apply any cash proceeds of Patents and Trademarks in any particular order of application. This Agreement shall be binding upon and inure to the benefit of the Debtor and the Secured Party and their respective participants, successors and assigns and shall take effect when signed by the Debtor and delivered to the Secured Party, and the Debtor waives notice of the Secured Party's acceptance hereof. The Secured Party may execute this Agreement if appropriate for the purpose of filing, but the failure of the Secured Party to execute this Agreement shall not affect or impair the validity or effectiveness of this Agreement. A carbon, photographic or other reproduction of this Agreement or of any financing statement signed by the Debtor shall have the same force and effect as the original for all purposes of a financing statement. This Agreement shall be governed by the internal law of Arizona without regard to conflicts of law provisions. If any provision or application of this Agreement is held unlawful or unenforceable in any respect, such illegality or unenforceability shall not affect other provisions or applications which can be given effect and this Agreement shall be construed as if the unlawful or unenforceable provision or application had never been contained herein or prescribed hereby. All representations and warranties contained in this Agreement shall survive the execution, delivery and performance of this Agreement and the creation and payment of the Obligations.

8. Prior Agreement. This Agreement amends and restates as of the date hereof, and continues the security interest granted in, the Patent and Trademark Security Agreement executed on or about February 6, 2004 by the Debtor and Wells Fargo Business Credit, Inc. (to whose interest the Secured Party has succeeded by merger), as amended and restated by that Amended and Restated Patent and Trademark Security Agreement executed on or about October 12, 2005 by the Debtor and the Secured Party.

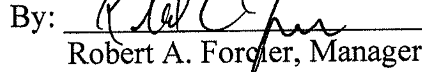
THE PARTIES WAIVE ANY RIGHT TO TRIAL BY JURY IN ANY ACTION OR PROCEEDING BASED ON OR PERTAINING TO THIS AGREEMENT.

TRADEMARK
REEL: 004659 FRAME: 0255

IN WITNESS WHEREOF, the parties have executed this Second Amended and Restated Patent and Trademark Security Agreement as of the date written above.

FlipChip International, LLC
3701 E. University Drive
Phoenix, Arizona 85034
Attn: Robert A. Forcier

FLIPCHIP INTERNATIONAL, LLC, a Delaware limited liability company



By: ______________________
Robert A. Forcier, Manager

Wells Fargo Bank, National Association
Wells Fargo Plaza, MAC S4101-158
100 West Washington Street, 15th Floor
Phoenix, Arizona 85003
Attn: Howard Handman

WELLS FARGO BANK, NATIONAL ASSOCIATION, acting through its Wells Fargo Business Credit operating division

By: ______________________
Howard Handman, Authorized Sigantory

IN WITNESS WHEREOF, the parties have executed this Second Amended and Restated Patent and Trademark Security Agreement as of the date written above.

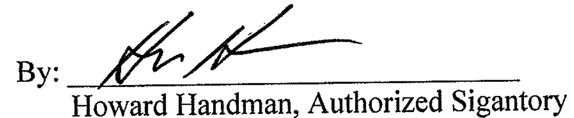
FlipChip International, LLC
3701 E. University Drive
Phoenix, Arizona 85034
Attn: Robert A. Forcier

FLIPCHIP INTERNATIONAL, LLC, a Delaware limited liability company

By: ____________________________
Robert A. Forcier, Manager

Wells Fargo Bank, National Association
Wells Fargo Plaza, MAC S4101-158
100 West Washington Street, 15th Floor
Phoenix, Arizona 85003
Attn: Howard Handman

WELLS FARGO BANK, NATIONAL ASSOCIATION, acting through its Wells Fargo Business Credit operating division

By: 
Howard Handman, Authorized Sigantory

STATE OF ARIZONA)
)ss
COUNTY OF MARICOPA)

The foregoing instrument was acknowledged before me this 30 day of September, 2011, by Robert A. Forcier, Manager of FLIPCHIP INTERNATIONAL, LLC, a Delaware limited liability company, on behalf of FlipChip International, LLC.

Dawn M. Cuevas
Notary Public

My Commission Expires:

06.24.12

STATE OF ARIZONA)
)ss
COUNTY OF MARICOPA)

The foregoing instrument was acknowledged before me this ___ day of September, 2011, by Howard Handman, the Authorized Signatory of WELLS FARGO BANK, NATIONAL ASSOCIATION, acting through its Wells Fargo Business Credit operating division, on behalf of the bank.

____
Notary Public

My Commission Expires:

____

STATE OF ARIZONA)
)ss
COUNTY OF MARICOPA)

The foregoing instrument was acknowledged before me this ___ day of September, 2011, by Robert A. Forcier, Manager of FLIPCHIP INTERNATIONAL, LLC, a Delaware limited liability company, on behalf of FlipChip International, LLC.

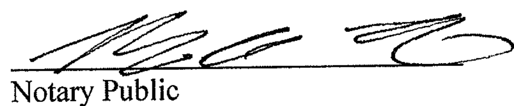
____
Notary Public

My Commission Expires:

____

STATE OF ARIZONA)
)ss
COUNTY OF MARICOPA)

The foregoing instrument was acknowledged before me this ___ day of September, 2011, by Howard Handman, the Authorized Signatory of WELLS FARGO BANK, NATIONAL ASSOCIATION, acting through its Wells Fargo Business Credit operating division, on behalf of the bank.



Notary Public

My Commission Expires:

7/29/2012

TRADEMARK
REEL: 004659 FRAME: 0259

EXHIBIT A

Patent List

[attached hereto]

TRADEMARK
REEL: 004659 FRAME: 0260

Greenberg Traurig LLP - Intellectual Property Department

Patent Report by Status

Client Name: FlipChip International, LLC (Small Entity)

DOCKET ID ALT ID	TECHNOLOGY/INVENTION TITLE	COUNTRY	STATUS SUBSTATUS	TYPE SUBTYPE	APP. DATE APP. NUMBER	GRANT DATE NUMBER	EXPIRATION DATE
053877-010500/US	Flexible Printed Circuit Board and Method for the Fabrication Thereof	United States of America	Inactive Expired	Patent Provisional	12/6/2002 60/431,239		12/6/2003
072145-010700/PCT 019905-004500PC	SCREEN PRINT UNDER-BUMP METALIZATION (UBM) TO PRODUCE LOW COST FLIP CHIP SUBSTRATE	PCT	Inactive Abandoned	Patent	5/7/2004 US04/14147		
072145-010700/US 019905-004500US	SCREEN PRINT UNDER-BUMP METALIZATION (UBM) TO PRODUCE LOW COST FLIP CHIP SUBSTRATE	United States of America	Inactive Abandoned	Patent Non-provisional application	5/8/2003 10/434,984		
072145-011400/US	Low Cost, Fine Pitch, High Input/Output Count Flip Chip Semiconductor Package	United States of America	Inactive Never filed	Patent			
072145-011500/PCT	SOLDER BUMP/UBM STRUCTURE FOR HIGH TEMPERATURE APPLICATIONS	PCT	Inactive 30 Months Term Over	Patent	12/6/2007 PCT/US07/86676		12/6/2011
072145-011500/US	SOLDER BUMP/UBM STRUCTURE FOR HIGH TEMPERATURE APPLICATIONS	United States of America	Pending Published	Patent Non-provisional application	12/11/2006 11/609,036		12/11/2026
072145-011501/EP	SOLDER BUMP/UBM STRUCTURE FOR HIGH TEMPERATURE APPLICATIONS	EPO	Pending Published	Patent	12/6/2007 07865323.5		12/6/2027
072145-011502/CN	SOLDER BUMP/UNDER BUMP METALLURGY STRUCTURE FOR HIGH TEMPERATURE APPLICATIONS	China	Pending Published	Patent	12/6/2007 200780045879.X		12/6/2027

TRADEMARK
REEL: 004659 FRAME: 0261

Greenberg Traurig LLP - Intellectual Property Department

Patent Report by Status

Client Name: FlipChip International, LLC (Small Entity)

DOCKET ID ALT ID	TECHNOLOGY/INVENTION TITLE	COUNTRY	STATUS SUBSTATUS	TYPE SUBTYPE	APP. DATE APP. NUMBER	GRANT DATE NUMBER	EXPIRATION DATE
072145-011503/KR	SOLDER BUMP/UBM STRUCTURE FOR HIGH TEMPERATURE APPLICATIONS	Korea (South)	Pending Nat. Phase	Patent	12/6/2007 10-2009-7013787		12/6/2027
072145-011504/TW	SOLDER BUMP/UNDER BUMP METALLURGY STRUCTURE FOR HIGH TEMPERATURE APPLICATIONS	Taiwan	Pending Published	Patent	11/29/2007 96145429		11/29/2027
072145-011600/PCT	FORMING PARTIAL-DEPTH FEATURES IN POLYMER FILM	PCT	Inactive 30 Months Term Over	Patent	9/27/2004 US04/31732		9/27/2008
072145-011600/US	FORMING PARTIAL-DEPTH FEATURES IN POLYMER FILM	United States of America	Granted	Patent Non-provisional application	9/26/2003 10/672,201	10/10/2006 7,118,833	9/26/2023
072145-011601/EP	FORMING PARTIAL-DEPTH FEATURES IN POLYMER FILM	EPO	Pending Published	Patent	9/27/2004 04809811.5		9/27/2024
072145-011602/CN	FORMING PARTIAL-DEPTH FEATURES IN POLYMER FILM	China	Granted	Patent	9/27/2004 200480030935.9	8/11/2010 ZL 200480030935.9	9/27/2024
072145-011603/KR	FORMING PARTIAL-DEPTH FEATURES IN POLYMER FILM	Korea (South)	Granted	Patent	9/27/2004 10-2006-7007999	1/9/2008 0794984	9/27/2024
072145-011700/US	METHOD FOR FORMING CHIP SCALE PACKAGE	United States of America	Granted	Patent Continuation	6/20/2001 09/885,846	6/15/2004 6,750,135	10/20/2017

TRADEMARK
REEL: 004659 FRAME: 0262

Greenberg Traurig LLP - Intellectual Property Department

Patent Report by Status

Client Name: FlipChip International, LLC (Small Entity)

DOCKET ID ALT ID	TECHNOLOGY/INVENTION TITLE	COUNTRY	STATUS SUBSTATUS	TYPE SUBTYPE	APP. DATE APP. NUMBER	GRANT DATE NUMBER	EXPIRATION DATE
072145-011800/US	METHOD FOR FORMING CHIP SCALE PACKAGE	United States of America	Granted	Patent Division	7/13/1998 09/114,204	9/11/2001 6,287,893	10/20/2017
072145-011900/PCT	POLYMER COLLAR FOR SOLDER BUMPS	PCT	Inactive 30 Months Term Over	Patent	9/21/2001 US01/29509		9/21/2005
072145-011900/US	POLYMER COLLAR FOR SOLDER BUMPS	United States of America	Granted	Patent Non-provisional application	9/22/2000 09/668,450	6/17/2003 6,578,755	9/22/2020
072145-011901/EP	POLYMER COLLAR FOR SOLDER BUMPS	EPO	Pending Published	Patent	9/21/2001 01971260.3		9/21/2021
072145-011902/KR	POLYMER COLLAR FOR SOLDER BUMPS	Korea (South)	Granted	Patent	9/21/2001 10-2003-7004188	2/9/2006 552943	9/21/2021
072145-011903/TW	POLYMER COLLAR FOR SOLDER BUMPS	Taiwan	Granted	Patent	9/21/2001 090123356	2/11/2003 NI-171691	9/21/2021
072145-012000/US	ELECTROLESS NI/PD/AU METALLIZATION STRUCTURE FOR COPPER INTERCONNECT SUBSTRATE AND METHOD THEREFOR	United States of America	Granted	Patent Non-provisional application	1/22/2001 09/766,798	9/3/2002 6,445,069	1/22/2021
072145-012000/US/2	ELECTROLESS NI/PD/AU METALLIZATION STRUCTURE FOR COPPER INTERCONNECT SUBSTRATE AND METHOD THEREFOR	United States of America	Inactive	Patent Re-examination	11/21/2008 90/009,338		11/21/2028

Greenberg Traurig LLP - Intellectual Property Department

Patent Report by Status

Client Name: FlipChip International, LLC (Small Entity)

DOCKET ID ALT ID	TECHNOLOGY/INVENTION TITLE	COUNTRY	STATUS SUBSTATUS	TYPE SUBTYPE	APP. DATE APP. NUMBER	GRANT DATE NUMBER	EXPIRATION DATE
072145-012100/PCT	SOLDER BAR FOR HIGH POWER FLIP CHIPS	PCT	Inactive 30 Months Term Over	Patent	5/17/2001 US01/15928		5/17/2005
072145-012100/US	SOLDER BAR FOR HIGH POWER FLIP CHIPS	United States of America	Granted	Patent Request for Cont. Examination	5/19/2000 09/575,298	6/6/2006 7,057,292	5/19/2020
072145-012101/EP	SOLDER BAR FOR HIGH POWER FLIP CHIPS	EPO	Granted	Patent	5/17/2001 01935623.7	5/11/2011 1305829	5/17/2021
072145-012102/EP/DE	SOLDER BAR FOR HIGH POWER FLIP CHIPS	Germany	Granted	Patent	5/17/2001 01935623.7	5/11/2011 1305829	5/17/2021
072145-012103/EP/FR	SOLDER BAR FOR HIGH POWER FLIP CHIPS	France	Granted	Patent	5/17/2001 01935623.7	5/11/2011 1305829	5/17/2021
072145-012300/NL	A METHOD OF FORMING A CHIP SCALE PACKAGE USING LARGE DUCTILE SOLDER BALLS	Netherlands	Inactive Abandoned	Patent	10/19/1998 98953717.0	3/4/2009 1036414	10/19/2018
072145-012300/PCT	CHIP SCALE PACKAGE USING LARGE DUCTILE SOLDER BALLS	PCT	Inactive 30 Months Term Over	Patent	10/19/1998 US98/22071		10/19/2002
072145-012300/US	CHIP SCALE PACKAGE USING LARGE DUCTILE SOLDER BALLS	United States of America	Granted	Patent CPA - Continued Prosecution App.	10/20/1997 08/954,426	8/27/2002 6,441,487	10/20/2017

TRADEMARK
REEL: 004659 FRAME: 0264

Greenberg Traurig LLP - Intellectual Property Department

Patent Report by Status

Client Name: FlipChip International, LLC (Small Entity)

DOCKET ID ALT ID	TECHNOLOGY/INVENTION TITLE	COUNTRY	STATUS SUBSTATUS	TYPE SUBTYPE	APP. DATE APP. NUMBER	GRANT DATE NUMBER	EXPIRATION DATE
072145-012301/EP	A METHOD OF FORMING A CHIP SCALE PACKAGE USING LARGE DUCTILE SOLDER BALLS	EPO	Granted	Patent	10/19/1998 98953717.0	3/4/2009 1036414	10/19/2018
072145-012302/EP	CHIP SCALE PACKAGE USING LARGE DUCTILE SOLDER BALLS	EPO	Pending Published	Patent Division	10/19/1998 09002209.6		10/19/2018
072145-012303/DE	A METHOD OF FORMING A CHIP SCALE PACKAGE USING LARGE DUCTILE SOLDER BALLS	Germany	Granted	Patent	10/19/1998 98953717.0	3/4/2009 69840636.2-08	10/19/2018
072145-012304/FI	A METHOD OF FORMING A CHIP SCALE PACKAGE USING LARGE DUCTILE SOLDER BALLS	Finland	Granted	Patent	10/19/1998 98953717.0	3/4/2009 1036414	10/19/2018
072145-012305/FR	A METHOD OF FORMING A CHIP SCALE PACKAGE USING LARGE DUCTILE SOLDER BALLS	France	Granted	Patent	10/19/1998 98953717.0	3/4/2009 1036414	10/19/2018
072145-012306/GB	A METHOD OF FORMING A CHIP SCALE PACKAGE USING LARGE DUCTILE SOLDER BALLS	United Kingdom	Granted	Patent	10/19/1998 98953717.0	3/4/2009 1036414	10/19/2018
072145-012307/JP	CHIP SCALE PACKAGE USING LARGE DUCTILE SOLDER BALLS	Japan	Granted	Patent	10/19/1998 2000-517447	9/3/2010 4580550	10/19/2018
072145-012308/KR	CHIP SCALE PACKAGE USING LARGE DUCTILE SOLDER BALLS	Korea (South)	Granted	Patent	10/19/1998 10-2000-7004263	1/2/2006 541827	10/19/2018

TRADEMARK
REEL: 004659 FRAME: 0265

Greenberg Traurig LLP - Intellectual Property Department

Patent Report by Status

Client Name: FlipChip International, LLC (Small Entity)

DOCKET ID ALT ID	TECHNOLOGY/INVENTION TITLE	COUNTRY	STATUS SUBSTATUS	TYPE SUBTYPE	APP. DATE APP. NUMBER	GRANT DATE NUMBER	EXPIRATION DATE
072145-012400/CN	WAFER-LEVEL MOAT STRUCTURES	China	Inactive Dropped	Patent	9/27/2004 200480030957.5		9/27/2024
072145-012400/EP	WAFER-LEVEL MOAT STRUCTURES	EPO	Inactive Abandoned	Patent	9/27/2004 04785094.6		9/27/2024
072145-012400/KR	WAFER-LEVEL MOAT STRUCTURES	Korea (South)	Inactive Abandoned	Patent	9/27/2004 10-2006-7008010		9/27/2024
072145-012400/PCT	WAFER-LEVEL MOAT STRUCTURES	PCT	Inactive 30 Months Term Over	Patent	9/27/2004 US04/31583		9/27/2008
072145-012400/US	WAFER-LEVEL MOAT STRUCTURES	United States of America	Granted	Patent Non-provisional application	9/26/2003 10/672,165	10/24/2006 7,126,164	9/26/2023
072145-012500/US	Build-Up Structures with Multi-Angle Vias for Chip to Chip Interconnects and Optical Bussing	United States of America	Granted	Patent Continuation	6/7/2005 11/145,948	3/14/2006 7,011,988	11/10/2023
072145-012600/PCT	SEMICONDUCTOR DEVICE PACKAGE WITH BUMP OVERLYING A POLYMER LAYER	PCT	Inactive 30 Months Term Over	Patent	10/28/2005 PCT/US05/39008		10/28/2009
072145-012600/US	HIGH PERFORMANCE CHIP SCALE PACKAGE FOR RADIO FREQUENCY DEVICES	United States of America	Inactive Expired	Patent Provisional	10/29/2004 60/623,200		10/29/2005

TRADEMARK
REEL: 004659 FRAME: 0266

Greenberg Traurig LLP - Intellectual Property Department

Patent Report by Status

Client Name: FlipChip International, LLC (Small Entity)

DOCKET ID ALT ID	TECHNOLOGY/INVENTION TITLE	COUNTRY	STATUS SUBSTATUS	TYPE SUBTYPE	APP. DATE APP. NUMBER	GRANT DATE NUMBER	EXPIRATION DATE
072145-012601/US	SEMICONDUCTOR DEVICE PACKAGE WITH BUMP OVERLYING A POLYMER LAYER	United States of America	Pending Published	Patent	10/28/2005 11/718,192		
072145-012602/CN	SEMICONDUCTOR DEVICE PACKAGE WITH BUMP OVERLYING A POLYMER LAYER	China	Granted	Patent	10/28/2005 200580045561.2	6/2/2010 ZL200580045561.2	10/28/2025
072145-012603/EP	SEMICONDUCTOR DEVICE PACKAGE WITH BUMP OVERLYING A POLYMER LAYER	EPO	Pending Published	Patent	10/28/2005 05824732.1		10/28/2025
072145-012800/US	HIGH SENSITIVITY THERMOPILE SENSOR SUITABLE FOR DIRECT CONTACT TEMPERATURE MEASUREMENTS	United States of America	Inactive Abandoned	Patent Provisional	1/25/2005 60/646,743		1/25/2006
072145-012900/US	PALM-SIZE VOC AND BREATH COMPONENT ANALYZER	United States of America	Inactive Abandoned	Patent Provisional	1/25/2005 60/646,744		1/25/2006
072145-014500/US 53877-010400VUT/US	Build-Up Structures with Multi-Angle Vias for Chip to Chip Interconnects and Optical Bussing	United States of America	Granted	Patent Non-provisional application	11/10/2003 10/704,131	6/19/2005 6,919,508	11/10/2023
072145-014500PR/US 53877-010400/US	Build-Up Structures with Multi-Angle Vias for Chip to Chip Interconnects and Optical Bussing	United States of America	Inactive Expired	Patent Provisional	11/8/2002 60/424,710		11/8/2003
072145-014600/US	WAFER-LEVEL INTERCONNECT FOR HIGH MECHANICAL RELIABILITY APPLICATIONS	United States of America	Inactive Expired	Patent Provisional	10/5/2006 60/849,657		10/5/2007

TRADEMARK
REEL: 004659 FRAME: 0267

Greenberg Traurig LLP - Intellectual Property Department

Patent Report by Status

Client Name: FlipChip International, LLC (Small Entity)

DOCKET ID / ALT ID	TECHNOLOGY/INVENTION TITLE	COUNTRY	STATUS / SUBSTATUS	TYPE / SUBTYPE	APP. DATE / APP. NUMBER	GRANT DATE / NUMBER	EXPIRATION DATE
072145-014601/PCT	WAFER-LEVEL INTERCONNECT FOR HIGH MECHANICAL RELIABILITY APPLICATIONS	PCT	Inactive / 30 Months Term Over	Patent	10/5/2007 / PCT/US07/80558		10/5/2011
072145-014601/US	WAFER-LEVEL INTERCONNECT FOR HIGH MECHANICAL RELIABILITY APPLICATIONS	United States of America	Pending / Published	Patent	10/4/2007 / 11/867,646		10/4/2027
072145-014602/EP	WAFER-LEVEL INTERCONNECT FOR HIGH MECHANICAL RELIABILITY APPLICATIONS	EPO	Pending / Published	Patent	10/5/2007 / 07873520.6		10/5/2027
072145-014603/TW	WAFER-LEVEL INTERCONNECT FOR HIGH MECHANICAL RELIABILITY APPLICATIONS	Taiwan	Pending / Published	Patent	10/5/2006 / 96137172		10/5/2026
072145-014604/CN	WAFER-LEVEL INTERCONNECT FOR HIGH MECHANICAL RELIABILITY APPLICATIONS	China	Pending / Published	Patent	10/5/2007 / 200780040017.8		10/5/2027
072145-014900/US / 072145-012700	SOLDER BUMP INTERCONNECT FOR IMPROVED MECHANICAL AND THERMO-MECHANICAL PERFORMANCE	United States of America	Inactive / Expired	Patent / Provisional	4/23/2007 / 60/913,337		4/23/2008
072145-014901/US	SOLDER BUMP INTERCONNECT FOR IMPROVED MECHANICAL AND THERMO-MECHANICAL PERFORMANCE	United States of America	Granted	Patent / Non-provisional application	4/21/2008 / 12/107,009	7/5/2011 / 7,973,418	11/25/2028
072145-014902/PCT	SOLDER BUMP INTERCONNECT FOR IMPROVED MECHANICAL AND THERMO-MECHANICAL PERFORMANCE	PCT	Inactive / 30 Months Term Over	Patent	4/22/2008 / PCT/US08/61186		4/22/2012

TRADEMARK
REEL: 004659 FRAME: 0268

Client Name: FlipChip International, LLC (Small Entity)

DOCKET ID / ALT ID	TECHNOLOGY/INVENTION TITLE	COUNTRY	STATUS / SUBSTATUS	TYPE / SUBTYPE	APP. DATE / APP. NUMBER	GRANT DATE / NUMBER	EXPIRATION DATE
072145-014903/TW	SOLDER BUMP INTERCONNECT FOR IMPROVED MECHANICAL AND THERMO-MECHANICAL PERFORMANCE	Taiwan	Pending / Published	Patent	4/23/2008 / 97114880		4/23/2028
072145-014904/CN	SOLDER BUMP INTERCONNECT FOR IMPROVED MECHANICAL AND THERMO-MECHANICAL PERFORMANCE	China	Pending / Published	Patent	4/22/2008 / 200880002933.7		4/22/2028
072145-014905/KR	SOLDER BUMP INTERCONNECT FOR IMPROVED MECHANICAL AND THERMO-MECHANICAL PERFORMANCE	Korea (South)	Pending / Nat. Phase	Patent	4/22/2008 / 10-2009-7014341		4/22/2028
072145-014906/EP	SOLDER BUMP INTERCONNECT FOR IMPROVED MECHANICAL AND THERMO-MECHANICAL PERFORMANCE	EPO	Pending / Published	Patent	4/22/2008 / 08746580.3		4/22/2028
072145-014907/US	SOLDER BUMP INTERCONNECT	United States of America	Pending / Published	Patent / Continuation	4/13/2011 / 13/085,759		4/21/2028
072145-016000/US	PROCESS AND METHOD FOR ENHANCED RELIABILITY FOR SEMICONDUCTOR PACKAGING USING DIELECTRIC ENCASEMENT	United States of America	Inactive / Expired	Patent / Provisional	8/7/2008 / 61/087,109		8/7/2009
072145-016001/PCT	ENHANCED RELIABILITY FOR SEMICONDUCTOR DEVICES USING DIELECTRIC ENCASEMENT	PCT	Inactive / 30 Months Term Over	Patent	8/7/2009 / PCT/US09/53205		8/7/2013
072145-016002/TW	ENHANCED RELIABILITY FOR SEMICONDUCTOR DEVICES	Taiwan	Pending / Published	Patent	8/10/2009 / 98126770		8/10/2029

TRADEMARK
REEL: 004659 FRAME: 0269

Client Name: FlipChip International, LLC (Small Entity)

DOCKET ID ALT ID	TECHNOLOGY/INVENTION TITLE	COUNTRY	STATUS SUBSTATUS	TYPE SUBTYPE	APP. DATE APP. NUMBER	GRANT DATE NUMBER	EXPIRATION DATE
072145-016003/US	ENHANCED RELIABILITY FOR SEMICONDUCTOR DEVICES USING DIELECTRIC ENCASEMENT	United States of America	Pending Published	Patent Non-provisional application	8/6/2009 12/537,236		8/6/2029
072145-016004/EP	ENHANCED RELIABILITY FOR SEMICONDUCTOR DEVICES USING DIELECTRIC ENCASEMENT	EPO	Pending Published	Patent National Phase	8/7/2009 09805628.6		8/7/2029
072145-016005/JP	ENHANCED RELIABILITY FOR SEMICONDUCTOR DEVICES USING DIELECTRIC ENCASEMENT	Japan	Pending	Patent National Phase	8/7/2009 2011-522294		8/7/2029
072145-016006/CN	ENHANCED RELIABILITY FOR SEMICONDUCTOR DEVICES USING DIELECTRIC ENCASEMENT	China	Pending	Patent National Phase	8/7/2009 200980139878.0		8/7/2029
072145-016007/KR	ENHANCED RELIABILITY FOR SEMICONDUCTOR DEVICES USING DIELECTRIC ENCASEMENT	Korea (South)	Pending	Patent National Phase	8/7/2009 10-2011-7005390		8/7/2029
072145-120000/US	UNDER BUMP METALLIZATION STRUCTURE HAVING A SEED LAYER FOR ELECTROLESS NICKEL DEPOSITION	United States of America	Inactive Expired	Patent Provisional	6/20/2007 60/945,310		6/20/2008
072145-120001/US	UNDER BUMP METALLIZATION STRUCTURE HAVING A SEED LAYER FOR ELECTROLESS NICKEL DEPOSITION	United States of America	Pending Published	Patent Non-provisional application	6/19/2008 12/142,415		6/19/2028
072145-120002/PCT	UNDER BUMP METALLIZATION STRUCTURE HAVING A SEED LAYER FOR ELECTROLESS NICKEL DEPOSITION	PCT	Inactive Abandoned	Patent	6/20/2008 PCT/US08/67795		6/20/2012

TRADEMARK
REEL: 004659 FRAME: 0270

Greenberg Traurig LLP - Intellectual Property Department

Patent Report by Status

Client Name: FlipChip International, LLC (Small Entity)

DOCKET ID ALT ID	TECHNOLOGY/INVENTION TITLE	COUNTRY	STATUS SUBSTATUS	TYPE SUBTYPE	APP. DATE APP. NUMBER	GRANT DATE NUMBER	EXPIRATION DATE
072145-120003/TW	UNDER BUMP METALLIZATION STRUCTURE HAVING A SEED LAYER FOR ELECTROLESS NICKEL DEPOSITION	Taiwan	Pending Published	Patent	6/20/2008 97123132		6/20/2028
072145-120004/EP	UNDER BUMP METALLIZATION STRUCTURE HAVING A SEED LAYER FOR ELECTROLESS NICKEL DEPOSITION	EPO	Pending Published	Patent	6/20/2008 08771684.1		6/20/2028
072145-120005/CN	UNDER BUMP METALLIZATION STRUCTURE HAVING A SEED LAYER FOR ELECTROLESS NICKEL DEPOSITION	China	Pending Published	Patent	6/20/2008 200880020888.8		6/20/2028
072145-120006/JP	UNDER BUMP METALLIZATION STRUCTURE HAVING A SEED LAYER FOR ELECTROLESS NICKEL DEPOSITION	Japan	Pending Published	Patent	6/20/2008 2010-513478		6/20/2028
072145-121000/US	Method for Building CU Pillar Interconnect	United States of America	Inactive Expired	Patent Provisional	7/2/2009 61/222,839		7/2/2010
072145-121001/US	METHODS AND STRUCTURES FOR A VERTICAL PILLAR INTERCONNECT	United States of America	Pending Published	Patent	6/30/2010 12/828,003		6/30/2030
072145-121002/PCT 072145-121000/PCT	METHODS AND STRUCTURES FOR A VERTICAL PILLAR INTERCONNECT	PCT	Pending Published	Patent	6/29/2010 PCT/US10/40410		6/29/2014
072145-121003/TW	METHODS AND STRUCTURES FOR A VERTICAL PILLAR INTERCONNECT	Taiwan	Pending Published	Patent	7/1/2010 99121741		7/1/2030

Greenberg Traurig LLP - Intellectual Property Department

Patent Report by Status

Client Name: FlipChip International, LLC (Small Entity)

DOCKET ID ALT ID	TECHNOLOGY/INVENTION TITLE	COUNTRY	STATUS SUBSTATUS	TYPE SUBTYPE	APP. DATE APP. NUMBER	GRANT DATE NUMBER	EXPIRATION DATE
072145-122000/US	*THIN FILM STRUCTURE FOR HIGH DENSITY INDUCTORS AND REDISTRIBUTION WAFER LEVEL PACKAGING*	*United States of America*	*Pending*	*Patent* *Provisional*	8/11/2011 *61/522,628*		*8/11/2012*

TRADEMARK
REEL: 004659 FRAME: 0272

EXHIBIT B

Trademark List

[attached hereto]

TRADEMARK
REEL: 004659 FRAME: 0273

Greenberg Traurig LLP - Intellectual Property Department

Trademark/Service Mark Report - Mark Status

FlipChip International, LLC (Small Entity)

COUNTRY/STATE STATUS SUBSTATUS	EFFECTIVE OWNER DOCKET ID NEXT DUE DATE		APP. DATE APP. NO. REG. DATE REG. NO. AFFIDAVIT DUE BASIS OF FILING	GOODS

DESIGN ONLY (for FlipChip)

United States of America Inactive Abandoned	FlipChip International, LLC (Small Entity) 072145-010900 7/27/2004	8 & 15 Reminder - 3 mo	10/17/1996 75/183,029 10/27/1998 2,199,271 10/27/2004 Actual Use	CUSTOM MANUFACTURE OF SEMICONDUCTOR WAFERS AND SEMICONDUCTOR CHIPS, NAMELY, APPLICATION OF SOLDER BUMPS TO SEMICONDUCTOR WAFERS AND SEMICONDUCTOR CHIPS

ELITECSP

United States of America Registered	FlipChip International, LLC (Small Entity) 072145-013800 11/6/2012	8 & 15 Reminder - 1 year	3/22/2006 78/843,235 11/6/2007 3,332,305 11/6/2013 Intention to Use	Class 40: Custom manufacture of semiconductor wafers and chips, namely solder bumps on electroless metal under bump metallurgy incorporating the adherence of solder spheres to electroless metal on semiconductor wafers and chips.

ELITEFC

United States of America Registered	FlipChip International, LLC (Small Entity) 072145-013700 11/6/2012	8 & 15 Reminder - 1 year	3/21/2006 78/841,899 11/6/2007 3,332,289 11/6/2013 Intention to Use	Class 40: Custom manufacture of semiconductor wafers and chips, namely solder bumps on electroless metal under bump metallurgy incorporating the adherence of solder spheres to electroless metal on semiconductor wafers and chips.

FlipChip International, LLC (Small Entity)

COUNTRY/STATE STATUS SUBSTATUS	EFFECTIVE OWNER DOCKET ID NEXT DUE DATE		APP. DATE APP. NO. REG. DATE REG. NO. AFFIDAVIT DUE BASIS OF FILING	GOODS

FLIPCHIP INTERNATIONAL

FLIPCHIP
INTERNATIONAL

United States of America	FlipChip International, LLC (Small Entity) 072145-011200		6/2/2004 78/428,930	Class 40: Custom manufacture of semiconductor wafers and semiconductor chips, namely, application of solder bumps to semiconductor wafers and semiconductor chips.
Registered Supplemental Register	7/26/2014	Renewal rmdr. - 1 year	7/26/2005 2,980,315 7/26/2011 Actual Use	

FLIPCHIP INTERNATIONAL VENTURES AND DESIGN

FLIPCHIP
INTERNATIONAL

United States of America	FlipChip International, LLC (Small Entity) 072145-013900		4/19/2006 78/865,082	Class 40: Operation of technology of third parties, namely custom manufacture of products in the wafer bumping and wafer scale packaging semiconductor market Class 42: Development of new technology for third parties in the wafer bumping and wafer scale packaging semiconductor market; and technology consultation in the wafer bumping and wafer scale packaging semiconductor market
Inactive Abandoned	6/11/2008	SOU/EOT Use or 1st Ext.6 Mo. (Deadline/Drop Dead)	Intention to Use	

FLIPCHIP TECHNOLOGIES & DESIGN

FlipChip International, LLC (Small Entity)

COUNTRY/STATE STATUS SUBSTATUS	EFFECTIVE OWNER DOCKET ID NEXT DUE DATE		APP. DATE APP. NO. REG. DATE REG. NO. AFFIDAVIT DUE BASIS OF FILING	GOODS
United States of America Inactive	FlipChip International, LLC (Small Entity) 072145-010800 7/20/2004	8 & 15 Reminder - 3 mo	10/17/1996 75/183,030 10/20/1998 2,197,002 10/20/2004 Actual Use	CUSTOM MANUFACTURE OF SEMICONDUCTOR WAFERS AND SEMICONDUCTOR CHIPS, NAMELY, APPLICATION OF SOLDER BUMPS TO SEMICONDUCTOR WAFERS AND SEMICONDUCTOR CHIPS

FOC FLEX-ON-CAP

FOC FLEX-ON-CAP

COUNTRY/STATE STATUS SUBSTATUS	EFFECTIVE OWNER DOCKET ID NEXT DUE DATE		APP. DATE APP. NO. REG. DATE REG. NO. AFFIDAVIT DUE BASIS OF FILING	GOODS
United States of America Inactive Abandoned	FlipChip International, LLC (Small Entity) 144540		7/2/2002 78/140,813 Intention to Use	042 - Wafer bumping services, and technology licensing related thereto, provided to third party manufacturers of integrated circuits
United States of America Inactive Abandoned	FlipChip International, LLC (Small Entity) 072145-010500 9/22/2004	Foreign Filing Reminder - 3 mo	6/22/2004 78/439,264 Intention to Use	Class 42: US 100 101. G & S: semiconductor assembly services for third party manufacturers of integrated circuits, namely, wafer level placement of under bump metalization and solder balls onto integrated electrical circuits

POWER WLP

TRADEMARK
REEL: 004659 FRAME: 0276

FlipChip International, LLC (Small Entity)

COUNTRY/STATE STATUS SUBSTATUS	EFFECTIVE OWNER DOCKET ID NEXT DUE DATE		APP. DATE APP. NO. REG. DATE REG. NO. AFFIDAVIT DUE BASIS OF FILING	GOODS
United States of America Inactive Abandoned	FlipChip International, LLC (Small Entity) 072145-010400 4/3/2003	Status Check__	7/3/2002 78/141,117 Intention to Use	SEMICONDUCTOR PACKAGING FOR MANUFACTURERS OF SEMICONDUCTORS AND DEVICES UTILIZING SEMICONDUCTORS, NAMELY, UNDER BUMP METALIZATION, POLYMER THIN FILM LAYERS AND SOLDER BUMPS CONSTRUCTED ON SEMICONDUCTORS WAFER TO PROTECT THE INTEGRATED CIRCUIT FROM CONTAMINANTS AND MOISTURE AND TO MAKE AN ELECTRICAL CONNECTION BETWEEN THE INTEGRATED CIRCUIT CHIP AND PRINTED CIRCUIT BOARD OR OTHER SUBSTRATES

SPHERON

COUNTRY/STATE STATUS SUBSTATUS	EFFECTIVE OWNER DOCKET ID NEXT DUE DATE		APP. DATE APP. NO. REG. DATE REG. NO. AFFIDAVIT DUE BASIS OF FILING	GOODS
United States of America Registered	FlipChip International, LLC (Small Entity) 072145-010600 3/1/2014	Renewal rmdr. - 1 year	9/27/2002 78/168,486 3/1/2005 2,929,612 3/1/2011 Intention to Use	Class 9: Semiconductor packaging for manufacturers of semiconductors and devices utilizing semiconductors, namely, under bump metalization, polymer thin film layers and solder bumps constructed on semiconductor wafer to protect the integrated circuit from contaminants and moisture and to make an electrical connection between the integrated circuit chip and printed circuit board or other substrates.

UCSP

FlipChip International, LLC (Small Entity)

COUNTRY/STATE STATUS SUBSTATUS	EFFECTIVE OWNER DOCKET ID NEXT DUE DATE		APP. DATE APP. NO. REG. DATE REG. NO. AFFIDAVIT DUE BASIS OF FILING	GOODS
United States of America Inactive Abandoned	FlipChip International, LLC (Small Entity) 072145-010300 11/11/2004	SOU/EOT Use or 2nd Ext.12 Mo. (Deadline/Drop Dead)	7/3/2002 78/141,122 Intention to Use	009 - semiconductor packaging for manufacturers of semiconductors and devices utilizing semiconductors, namely, under bump metalization, polymer thin film layers and solder bumps constructed on semiconductor wafer to protect the integrated circuit from contaminants and moisture and to make an electrical connection between the integrated circuit chip and printed circuit board or other substrates

ULTRA CSP

***Ultra* CSP**

COUNTRY/STATE STATUS SUBSTATUS	EFFECTIVE OWNER DOCKET ID NEXT DUE DATE		APP. DATE APP. NO. REG. DATE REG. NO. AFFIDAVIT DUE BASIS OF FILING	GOODS
United States of America Registered	FlipChip International, LLC (Small Entity) 072145-111000 10/9/2010	Renewal rmdr. - 1 year	8/27/1997 75/347,767 10/9/2001 2,496,509 10/9/2007 Actual Use	Class 9: Intergrated circuits incorporating solder bumps; Class 35: Packaging of integrated circuits to the order and specification of others.

TRADEMARK

RECORDED: 11/10/2011

REEL: 004659 FRAME: 0278